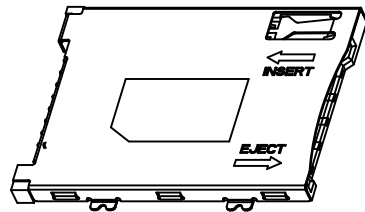


RoHS

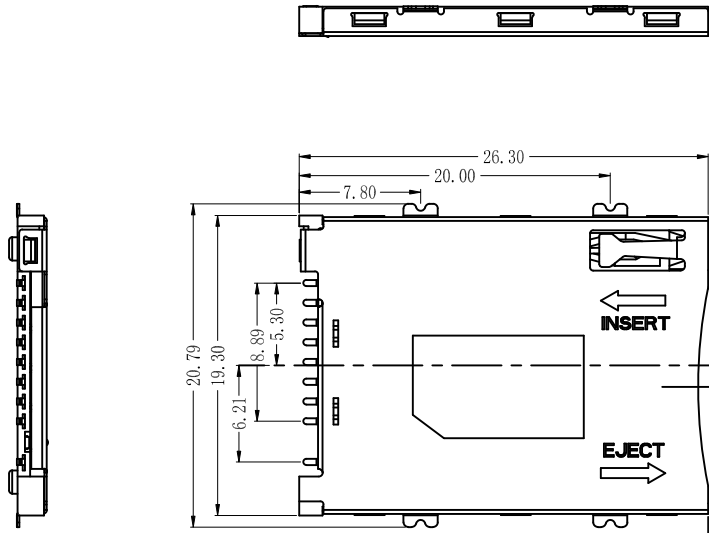
REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25



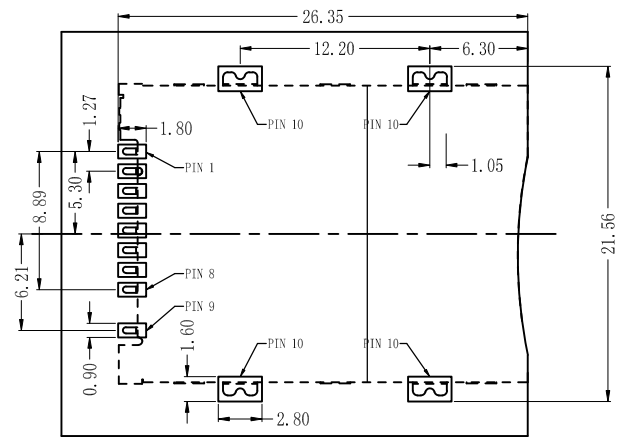
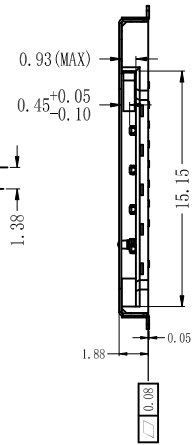
- NOTES:
- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0, COLOR: BLACK
CONTACT: COPPER ALLOYS
COVER: COPPER ALLOYS OR STEEL
 - PLATING:
UNDERPLATE: NICKEL
CONTACT AREA: GOLD OVER NICKEL
SOLDER AREA: TIN OVER NICKEL
 - MULTIMEDIA CARD COMPATIBLE

订购须知:
SMP11-S1S1-2000-A
1

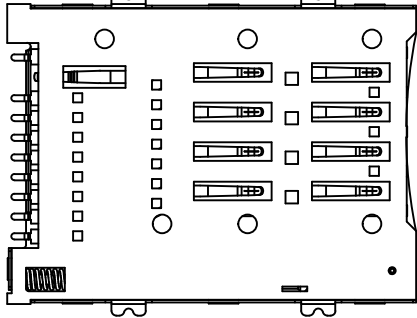
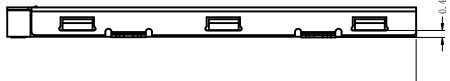
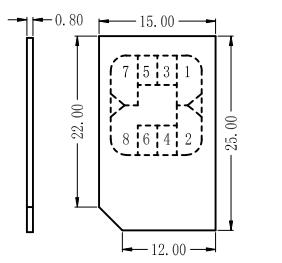
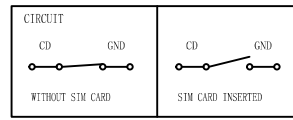
1.说明
11=无定位柱
21=有定位柱



(1.00) LOCATION OF CARD PUSHED
(2.00) LOCATION OF CARD LOCK
(6.00) LOCATION OF CARD EJECTED



RECOMMENDED P. C. B HOLE LAYOUT
COMPONENT SIDE VIEW (TOLERANCE: +/-0.05)



PIN NO.	NAME
PIN 1	VCC
PIN 2	GND
PIN 3	RST
PIN 4	VPP
PIN 5	CLK
PIN 6	I/O
PIN 7	DATO
PIN 8	MCMD
PIN 9	CARD DETECT Switch
PIN 10	GND

X±0.50	X°±
.X±0.25	.X°±
.XX±0.15	.XX°±
.XXX±0.10	.XXX°±
UNITS:	mm

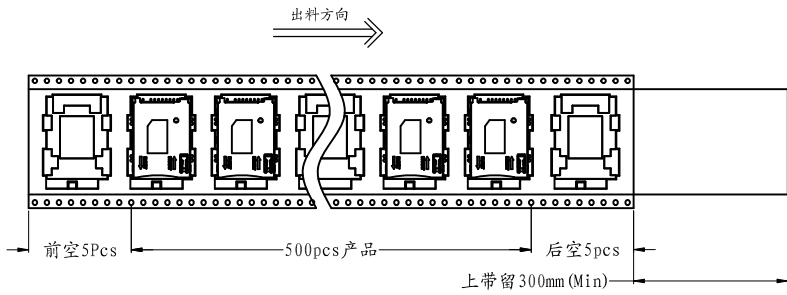
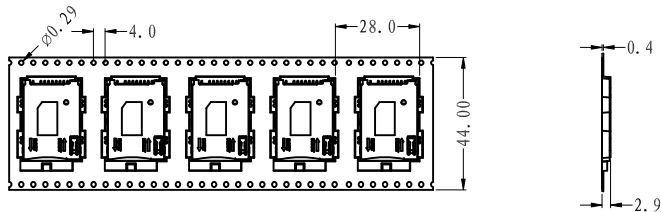
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUEID IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN

PART NO: SMP11-S1S1-2000-A	
TITLE: SIM PUSN卡座 1.9H	
APPD	
CHKD	Wang
DRAW	Wang
DATE	2024.01.20

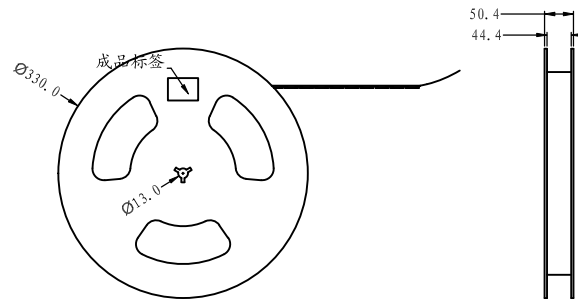
XFCN 兴飞连接器				
0769-82001899				
www.xfconn.com				
DWG NO: /				
VIEW				
SCALE	SHEET	REV		
NONE	1:1	A1		

RoHS

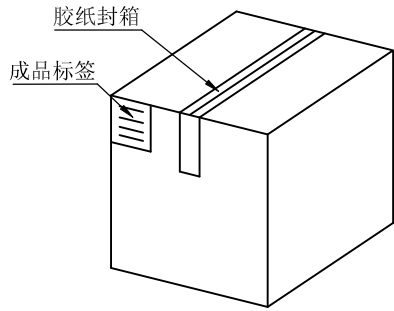
REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25



NO. 1

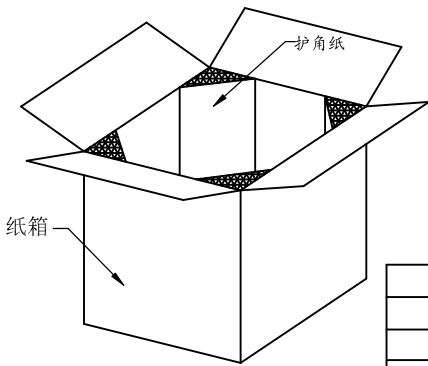
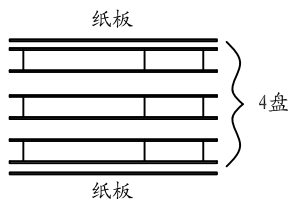


NO. 2



纸箱规格: 340*340*220

NO. 4



NO. 3

1. 材质要求:
 - 1.1 纸箱的材质为K=K;外形尺寸为34*34*22;
 - 1.2 卷盘的材质为PS,卷盘的外形尺寸为 $\varnothing 330*30.4$;
2. 包装方式:
 - 2.1 将卷带放入包装机后, 前空5PCS, 后放产品500PCS再后空5PCS;上带留200mm长度。
 - 2.2 将包装好的产品从包装机上取下并包装好,贴上内盘标签;
 - 2.3 把累叠好的4盘叠放入纸箱中共计2.0Kset, 每盘放纸板,
 - 2.4 把包装好的成品打包封箱, 并在纸箱外贴上标签

X. ± 0.50	X. $^{\circ} \pm$	PART NO:		SMP11-S1S1-2000-A		XFCN 兴飞连接器			
.X ± 0.25	.X $^{\circ} \pm$	TITLE:		SIM PUSN卡座 1.9H					0769-82001899
.XX ± 0.15	.XX $^{\circ} \pm$	UNITS:		mm		www.xfconn.com			
.XXX ± 0.10	.XXX $^{\circ} \pm$	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED, COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN		APPD		DWG NO: /			
				CHKD		VIEW			
				DRAW		SCALE		SHEET	REV
				DATE		NONE		1:1	A1
				Wang		2024.01.20			

XFCN 东莞市兴飞连接器有限公司

1. SCOPE 适用范围

This specification covers performance, tests and quality requirements for SIM MEMORY CARD CONNECTOR. These connectors are provide space savings and improved functionality to system signal transfer.

此规范包括性能, 测试及质量要求, 适用于 SIM 卡连接器, 提供完善的功能系统信号传输。

2. APPLICABLE DOCUMENTS 适用文件

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

下列文件构成本规范的一部分, 以本文规定的范围内。除另有规定外, 该规范的最新版本适用。在此规范之间的冲突和产品图纸要求的情况下, 产品图纸为准。

2. 1. Commercial standards, specifications and report 商业标准, 规格及报告

2. 1. 1. MIL-STD-1344A 根据MIL - STD - 1344A 标准

2. 1. 2. MIL-STD-202F 根据MIL - STD - 202F标准

3. REQUIREMENTS 要求

3.1. Design and Construction 设计与装配

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

产品应在设计, 装配和结构尺寸指定适用产品图纸。

3.2. Materials and Finish 材料与处理

3. 2. 1. Contact : High performance copper alloy (Phosphor Bronze)

Finish : (a) Contact Area: Gold over Nickel.

(b) Solder Tail area: Gold over Nickel.

端子: 高性能铜合金 (磷青铜)

表面处理: (a) 接触区域: 打镍底, 镀金。

(b) 焊接区域: 打镍底, 镀金。

3. 2. 2. Housing : LCP+30%G.F, UL94V-0.

胶芯材质: LCP +30 % 玻璃纤维, 耐燃指数: UL94V - 0。

3.3. Ratings 评定标准

3. 3. 1. Voltage : 500 Volts DC, AC(rms)250 Volts (per pin)

耐电压: 500伏特直流, 250伏特交流 (rms)

3. 3. 2. Current : 0.5 Amperes DC (per pin)

SPEC NO.		REV	B/0	ECN NO.		PAGE	1 / 3
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最大电流：0.5安培直流

3.3.3. Operating Temperature : -25°C TO +85°C
使用温度：-25°C至+85°C

3.4. Performance and Test Description 性能及测试说明

Product is designed to meet electrical, mechanical and environmental performance requirements specified in Paragraph 3.5. All tests are performed at ambient environmental conditions per MIL-STD-1344A unless otherwise specified.

产品的目的是为了满足不同电气，机械和环境性能要求在指定的第 3.5 节。所有测试是在常压环境条件按照 MIL - STD- 1344A 完成除非另有说明。

3.5. Test Requirements and Procedures Summary 测试要求和程序说明。

Test Description 测试说明	Finally 测试结果	Condition 测试条件					
ELECTRICAL (电气)							
Low-Signal Level Contact Resistance 接触电阻测试	R<100 mΩ 电阻小于 100mΩ	Mate subject connector with compatible connector as shown in. MIL-STD-202F, Method 302 500±10 %伏特之间的相邻或接触交配连接器为一分钟。 根据MIL - STD - 202F ,方法302。					
Insulation Resistance 绝缘电阻测试	R>1000 MΩ 绝缘电阻大于1000MΩ	Apply DC 500±10% Volts between adjacent contacts of mated connectors for one minute. MIL-STD-202F, Method 302 500±10 %伏特之间的相邻或接触交配连接器为一分钟。 根据 MIL - STD - 202F, 方法 302。					
Dielectric Withstanding Voltage 介质耐电压	No discharge, flashover or breakdown. 没有放电, 烧焦或击穿。	500 V initial and 250 Vfinal for 1 minute. MIL-STD-202F, Method 301 500V 和 250V 持续一分钟。 根据 MIL - STD - 202F, 方法 301。					
Retention Force 端子保持力	100 Gram(0.98N) minimum(per pin) 100 克 (0.98N) 最低 (每 pin)	Mate connector with a suitable gauge for each pin at rate of 25 mm/min. MIL-STD-1344A, Method 2012.1 用连接器与一个合适的拉力计, 每个管脚在速度为 25 毫米/每分钟情况下。 根据 MIL - STD - 1344A, 方法 2012.1					
SPEC NO.		REV	B/0	ECN NO.		PAGE	2 / 3

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<p>Vibration 振动测试</p>	<p>Discontinuity 1.0 microsec. MAX 瞬断不超过1毫秒</p>	<p>Mate dummy card and subject to following Vibration conditions for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1 mA during Amplitude: 1.52 mm P-P Frequency: 10-55-10 Hz Shall be traversed in 1 minute (MIL STD – 202 Method 201) 振幅: 1.52毫米P-P 频率: 10-55-10赫兹 每种频率持续一分种循环</p>					
<p>Durability 寿命周期测试</p>	<p>5000 cycles. 插拔 5000 次以上。</p>	<p>The sample should be mounted in the at the rate of 25mm/min. MIL-STD-1344A, Method 2016 样品应装在试验机, 在指定的速 25mm/min。 根据 MIL - STD - 1344A, 方法 2016</p>					
<p>Solderability 可焊性测试</p>	<p>Solderable area shall have minimum of 95% solder coverage. 可焊面积大于 95 %</p>	<p>Subject the test area of contacts into flux for 3±0.5 seconds and then into solder bath, controlled at 270±5°C, for 3±0.5 seconds. 持需焊部分放入锡炉, 温度控制在270 ± 5 °C, 为3 ± 0.5秒。</p>					
<p>ENVIRONMENTAL (环境)</p>							
<p>Salt Spray 氧化测试</p>	<p>Oxidation of not more than 5% 氧化面积不超过5%</p>	<p>Subject mated/unmated connectors to 5±1% salt-solution concentration, 35°C±2°C for 24 hours (Gold over for 24 H, Nickel for 24 H, Tin for 8 H) . MTL-STD-1344A, Method 1001.1, 以5 ± 1 %的盐溶液浓度, 35 °C ± 2 °C, 24小时(镀金区域24小时, 镀镍区域24小时, 镀锡区域8小时)。 MTL-STD-1344A 1001.1</p>					
<p>Temperature Life (Heat Aging) (Heat Resistance) 高温测试 (热老化) (耐热)</p>	<p>A.Products in 85 °C ± 2 °C 96 hours, the product can still be used normally. B.Products in the 260 °C ± 5 °C or eight of the reflow temperature (maximum temperature of 260 °C), the deformation of not more than 0.08 mm. A. 产品在85°C±2°C96小时, 产品仍可正常使用。 B. 产品在260°C±5°C或过八温段回流焊(最高温度260°C)后, 变形不超过0.12mm。</p>	<p>MTL-STD-202F, Method 108A,</p>					
SPEC NO.		REV	B/0	ECN NO.		PAGE	3 / 3